

ENGINEERING DEPT.		PRODUCT SPECIFICATION For CI88 Series Connector System	SPEC.NO.: SPCI134B
REVISIONS	ECNT121010		PAGE: 1/3

1. SCOPE:

This specification contains the test requirement of subject connectors when tested under the condition and procedure with terminals crimped on the specified maximum size wire

2. APPLICABLE STANDARDS:

MIL - STD - 202	Methods for test of connectors for electronic equipment
EIA - 364	Test methods for electrical connectors
SS-00254	Test methods for electronic components ,LEAD-FREE soldering Part design standards

3. APPLICABLE SERIES NO.: CI88 Series

4. SHAPE, CONSTRUCTION AND DIMENSIONS

See attached drawings

5. MATERIALS

See attached drawings

6. ACCOMMODATED P.C.BOARD

6.1 Thickness: 1.6 mm (.063")

6.2 P.C. Board Layout: See attached drawings



REVIEWED : Eisley APPROVED : Sun VERIFIED : Eric .

ENGINEERING DEPT.		PRODUCT SPECIFICATION For CI88 Series Connector System	SPEC.NO.: SPCI134B
REVISIONS	ECNT121010		PAGE: 2/3

7. ELECTRICAL PERFORMANCE:

	ITEM	TEST CONDITION	REQUIREMENT
7.1	Rated current and voltage		4A 250V AC (r.m.s.)
7.2	Contact resistance	Dry circuit of DC 20 mV max. , 100 mA max.	Less than 10 mΩ
7.3	Dielectric strength	When applied AC 750 V 1 minute between adjacent terminal	No change
7.4	Insulation resistance	When applied DC 500 V between adjacent terminal or ground	More than 5000 MΩ

8. MECHANICAL PERFORMANCE:

	ITEM	TEST CONDITION	REQUIREMENT
8.1	Pin retention force	Push pin from insulator base at speed 25± 3 mm per minute	More than 1.36 Kgf

9. ENVIRONMENTAL PERFORMANCE:

	ITEM	TEST CONDITION	REQUIREMENT
9.1	Temperature rise	Then carried the rated current	30 °C max.
9.2	Vibration	1.5 mm 10-55-10 HZ / minute each 2 hours for X , Y and Z directions	Appearance: No damage Discontinuity: 1 micro second max.
9.3	Solder ability	Tin-Lead Process: Soldering time: 5 ± 0.5 second Soldering pot: 230 ± 5 °C Lead-Free Process: Soldering time: 3 ± 0.5 second Soldering pot: 245 ± 5 °C	Minimum: 90% of immersed area
9.4	Resistance to soldering heat	Tin-Lead Process: Soldering time: 5 ± 0.5 second Soldering pot: 240 ± 5 °C Lead-Free Process Soldering time: 5 ± 0.5 second Soldering pot: 260 ± 5 °C	No damage

ENGINEERING DEPT.		PRODUCT SPECIFICATION For CI88 Series Connector System	SPEC.NO.: SPCI134B
REVISIONS	ECNT121010		PAGE: 3/3

	ITEM	TEST CONDITION	REQUIREMENT
9.5	Heat aging	85 ± 2 °C , 96 hours	No damage
9.6	Humidity	40 ± 2 °C , 90-95% RH , 96 hours measurement must be taken within 30 min. after tested	Appearance: No damage Contact resistance: Less than twice of initial Dielectric strength: To pass para 7-3
9.7	Temperature cycling	One cycle consists of : (1) -55 ⁺⁰ / ₋₃ °C , 30 min. (2)Room temp. 10-15 min. (3) 105 ⁺³ / ₋₀ °C , 30 min. (4)Room temp. 10-15 min. Total cycles: 5 cycles	Appearance: No damage Contact resistance: Less than twice of initial
9.8	Salt spray	Temperature: 35 ± 3 °C Solution: 5 ± 1% Spray time: 48 ± 4 hours (Stamping before plated) Spray time: 24 ± 4 hours (Stamping after plated) Mate connectors and expose to the following salt mist conditions. Upon completion of the exposure period, salt deposits shall be removed by a gentle wash or dip in running water and dried naturally, after which the specified measurements shall be performed. The specimens shall be suspended from the top using waxed twine, string or nylon thread. The test only define the plating area, without plating area (as copper cross section) will not be defined. (EIA 364-26B / MIL-STD-202 Method 101)	Appearance: No damage Contact resistance: Less than twice of initial

10. AMBIENT TEMPERATURE RANGE: -55 to + 105 °C(Including terminal temperature rise)